

## REMARKS

Claims 1-14 were pending, of which Claims 10-14 were withdrawn from consideration. Claims 1-9 were rejected. Claims 10-14 have been cancelled and Claims 15-24 added.

### Specification

The Specification has been amended to include the patent number and issue date for references that were cited therein.

### Double Patenting

Claims 3-6 were rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 33-35 of U.S. Patent No. 6,320,609 (the '609). Enclosed is a terminal disclaimer executed by the undersigned, which overcomes this ground of rejection. Accordingly, Applicants respectfully submit that Claims 3-6 are now in condition for allowance.

### Claim Rejections – 35 U.S.C. §102

Claims 1, 7, and 9 were rejected under 35 U.S.C. §102(b) as being anticipated by Cheng (5,546,179) ("Cheng '179"). The Examiner stated that "Cheng '179 discloses (Fig. 2) placing a wafer at a fixed chuck (64)..." Applicants respectfully traverse.

In the description of Fig. 2, Cheng '179 states "[I]n step 64, a wafer 22 is placed on chuck 16 as described in reference to Fig. 1." Col. 7, lines 17-19. Referring to Fig. 1, Cheng '179 expressly teaches the use of a chuck assembly 12 that includes a "rotatable chuck 16." Col. 5, lines 15-16. Applicants are not aware of a teaching or suggestion in Cheng '179 that the chuck 16 may be "fixed".

Accordingly, Claim 1, which recites "positioning a wafer at a fixed station" is not taught or suggested in Cheng '179.

Thus, Applicants respectfully submit that Claim 1 is patentable over Cheng '179. Reconsideration and withdrawal of this rejection is respectfully requested. Claims 2-9 depend from Claim 1 and are, therefore, likewise patentable.

### Claim Rejections – 35 U.S.C. §103

Claims 1-2 and 7-9 were rejected under 35 U.S.C. §103(a) as being unpatentable over Cheng (6164,894) (Cheng '894). The Examiner stated that "Cheng '894 teaches positioning (and then testing) a wafer in a fixed station (16) (col. 1 line 55-col. 2 line 25)". Applicants respectfully traverse.

At col. 1, line 55 to col. 2, line 17, Cheng '894 describes the problems associated with "the prior art method" which requires that the wafer be "transported from the edge mapping platform to a different test chuck for testing or processing." The "prior art method" is described by Cheng '894 at col. 1, lines 44-54. Notably, Cheng '894 states that the "wafer is positioned on a rotatable platform, where the edge of the wafer is positioned within or over a sensor. The platform is rotated, and the position of the edge of the wafer is detected by the sensor throughout the entire 360-degree rotation." Col. 1, lines 44-48. Thus, Cheng '894 is not describing a system where the wafer is at a fixed position. In addition, Cheng '894 goes on to describe the chuck assembly 16 in Fig. 1, stating that "the chuck 84 is rotatable about a central z-axis". Applicants are not aware of a teaching or suggestion in Cheng '894 that the chuck is "fixed".

Accordingly, Claim 1, which recites "positioning a wafer at a fixed station" is not taught or suggested in Cheng '894.

Thus, Applicants respectfully submit that Claim 1 is patentable over Cheng '894. Reconsideration and withdrawal of this rejection is respectfully requested. Claims 2-9 depend from Claim 1 and are, therefore, likewise patentable.

Claims 15-24 have been added. Support from Claims 15-24 is found in originally filed Claims 1-9 as well as in the figures and accompanying text. No new matter has been added.

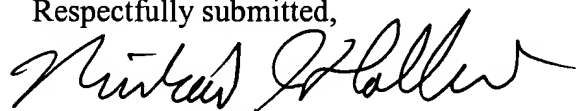
Applicants point out that Claim 15 recites "locating an alignment feature on the edge of the wafer, wherein locating the alignment feature comprises moving the optical system to locate an edge of the wafer, and moving the optical system rotationally to follow the edge of the wafer" which is not taught or suggested in either Cheng '179 or Cheng '894 (or Yarussi et al. (6,181,427)). Moreover, Claim 21 recites "imaging at least one inspection area on the wafer using the optical system; and rotating the image of an inspection area based on the

relative angular orientation of the optical system with the wafer" which is not taught or suggested in either Cheng '179 or Cheng '894 (or Yarussi et al. (6,181,427)).

Claims 1-9 and 15-23 are pending, of which Claims 15-23 have been added. For the above reasons, Applicants respectfully request allowance of Claims 1-9 and 15-23. Should the Examiner have any questions concerning this response, the Examiner is invited to call the undersigned at (408) 982-8200, ext. 2.

**Via Express Mail Label No.  
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Respectfully submitted,



Michael J. Halbert  
Attorney for Applicants  
Reg. No. 40,633

SILICON VALLEY  
PATENT GROUP LLP

2350 Mission College Blvd.  
Suite 360  
Santa Clara, CA 95054  
(408) 982-8200  
FAX (408) 982-8210